

Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

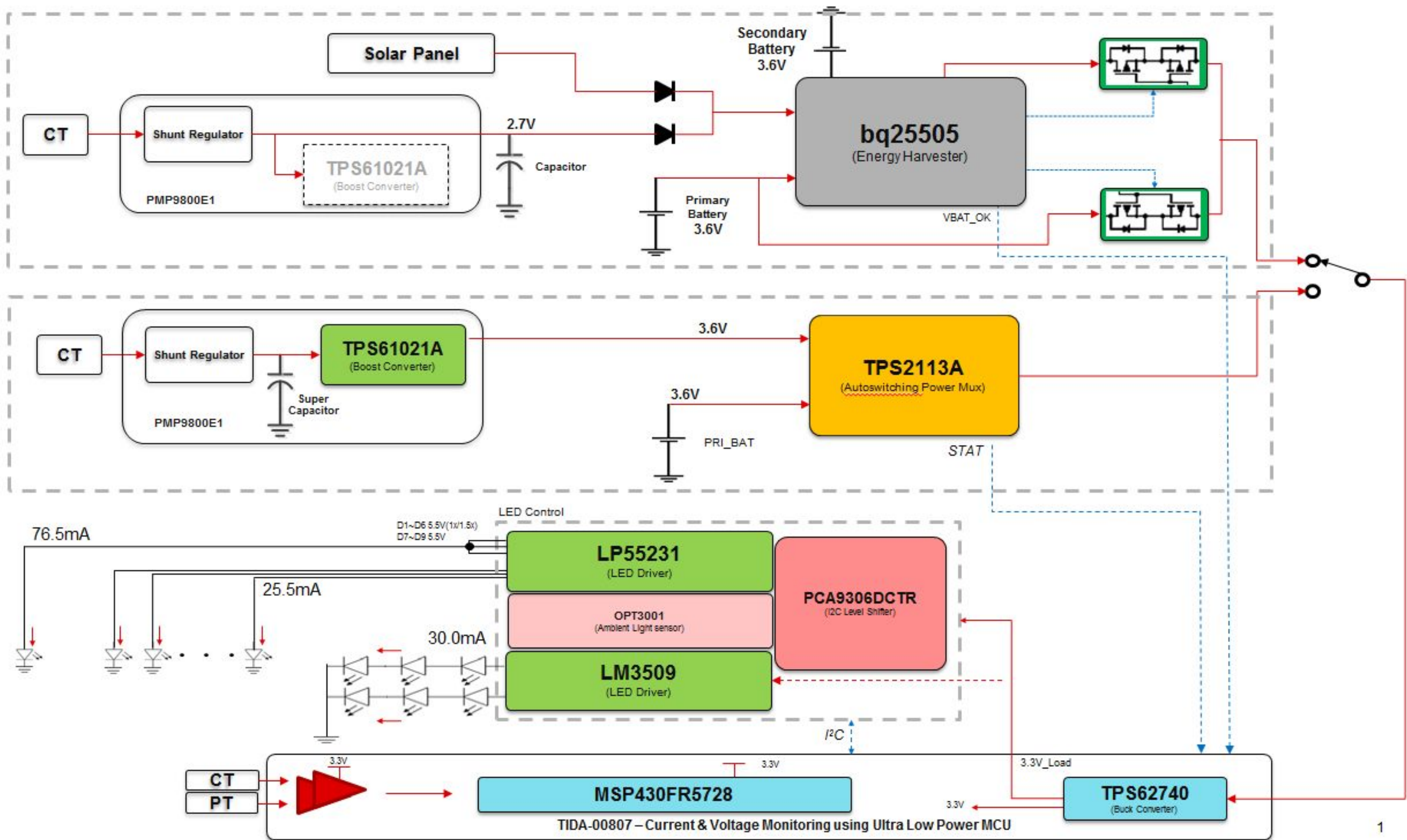
Page 2 BLOCK DIAGRAM

Page 3 Energy Harvesting & FI Subsystem For OHFI

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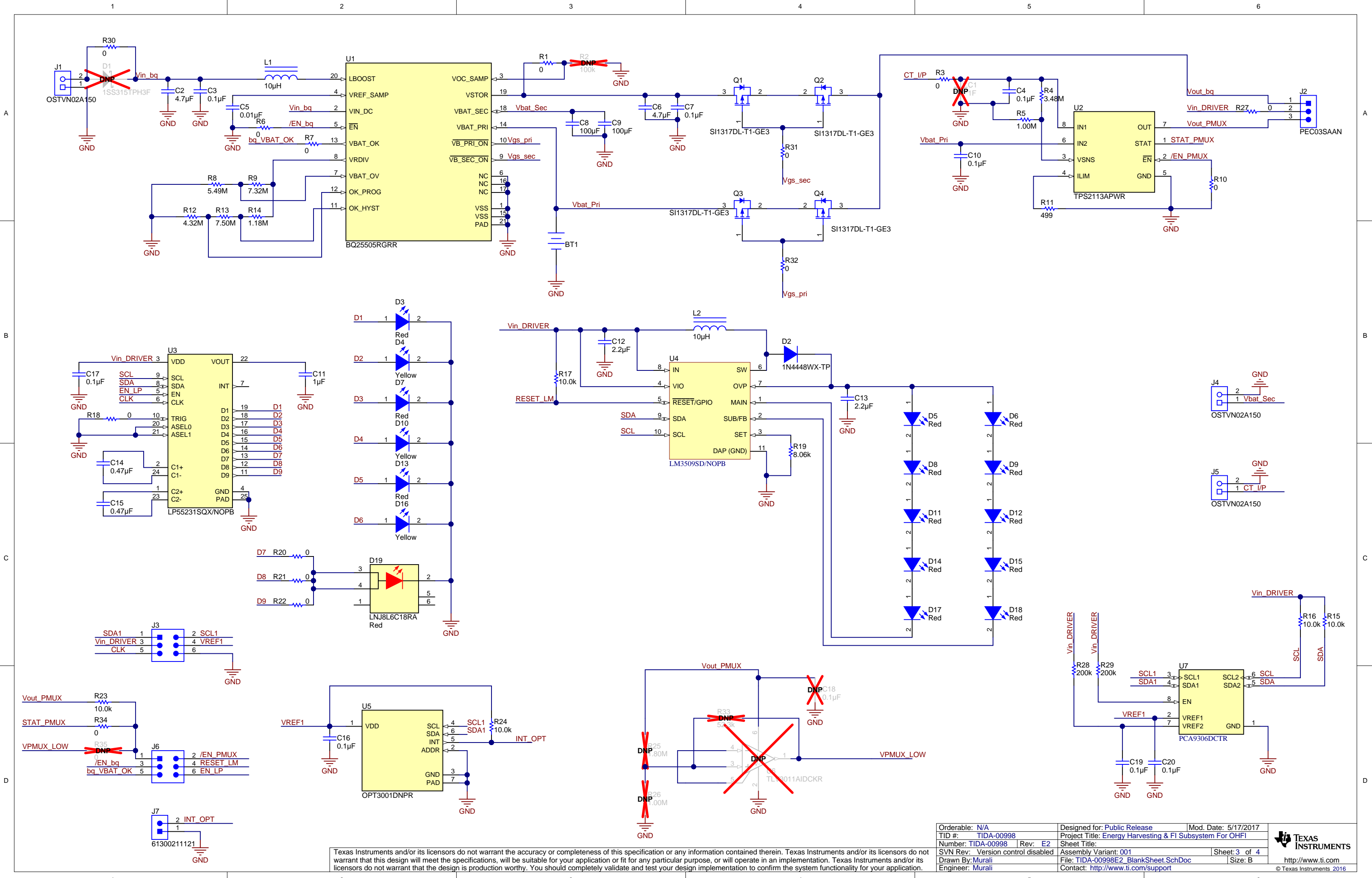
Orderable: N/A	Designed for: Public Release	Mod. Date: 3/16/2017
TID #: TIDA-00998	Project Title: Energy Harvesting & FI Subsystem For OHFI	
Number: TIDA-00998	Rev: E2	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 4
Drawn By: Murali	File: TIDA-00998E2_CoverSheet.SchDoc	Size: B
Engineer: Murali	Contact: http://www.ti.com/support	http://www.ti.com





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TID #: TIDA-00998	Project Title: Energy Harvesting & FI Subsystem For OHFI	
Number: TIDA-00998	Rev: E2	Sheet: 2 of 4
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B
Drawn By: Murali	File: TIDA-00998E2_Block Diagram_SchDoc	Contact: http://www.ti.com/support
Engineer: Murali		



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Orderable: N/A	Designed for: Public Release	Mod. Date: 5/17/2017
TID #: TIDA-00998	Project Title: Energy Harvesting & FI Subsystem For OHFI	
Number: TIDA-00998	Rev: E2	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 4
Drawn By: Murali	File: TIDA-00998E2_BlankSheet_SchDoc	Size: B
Engineer: Murali	Contact: http://www.ti.com/support	



A

A



PCB Number: TIDA-00998
PCB Rev: E2

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.

B

B

Variant/Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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